

Power Supply Input

Var	Value	Units	Description
VACMIN	85	V	Minimum Input AC Voltage
VACMAX	265	V	Maximum Input AC Voltage
FL	50	Hz	Line Frequency
TC	2.70	ms	Diode Conduction Time
Z	0.50		Loss Allocation Factor
η	78.0	%	Efficiency Estimate
VMIN	82.6	V	Minimum DC Input Voltage
VMAX	374.8	V	Maximum DC Input Voltage

Input Section

Var	Value	Units	Description
Fuse	1.00	A	Input Fuse Rated Current
IAVG	0.35	A	Average Diode Bridge Current (DC Input Current)
Thermistor	16.00	Ω	Input Thermistor
MOV_VRATE D	275	V	MOV Rated Voltage

Device Variables

Var	Value	Units	Description
Device	TNY290PG		PI Device Name
Device Mode	Increased		Current Limit mode for device
PO	22.80	W	Total Output Power
VDRAIN Estimated	605.01	V	Actual Estimated Drain Voltage
VDS	4.57	V	On state Drain to Source Voltage
I2F_MIN	85.83	A ² kHz	Minimum I2F
I2F_MAX	110.63	A ² kHz	Maximum I2F
FS_AT_ILIMM IN	137183	Hz	Switching Frequency at Current Limit Minimum
KP	0.41		Continuous/Discontinuous Operating Ratio
KP_TRANSIE NT	0.29		Transient Ripple to Peak Current Ratio
ILIMITMIN	0.79	A	Minimum Current Limit
ILIMITMAX	0.94	A	Maximum Current Limit
RLS	2.0	M Ω	Line sense resistor
RLS2	2.0	M Ω	Line sense resistor
IRMS	0.49	A	Primary RMS Current (at VMIN)
P_NO_LOAD	150	mW	Estimated No Load Input Power
DMAX	0.57		Maximum Duty Cycle
RTH_DEVICE	46.26	$^{\circ}$ C/W	PI Device Maximum Thermal Resistance
DEV_HSINK_ TYPE	2 Oz (70 μ) Copper PCB		PI Device Heatsink Type
DEV_HSINK_ AREA	262	mm ²	PI Device Heatsink Area

Clamp Circuit

Var	Value	Units	Description
Clamp Type	RCD Clamp		Clamp Circuit Type
VCLAMP	175	V	Estimated average clamping voltage
Estimated Clamp Loss	1.04	W	Clamp Dissipation

Transformer Construction Parameters

Var	Value	Units	Description
Core Type	E25/13/7 (EF25)		Core Type

Core Material	NC-2H (Nicera) or Equivalent		Core Material
Bobbin Reference	Generic, 5 pri. + 5 sec.		Bobbin Reference
Bobbin Orientation	Vertical		Bobbin type
Primary Pins	4		Number of Primary pins used
Secondary Pins	3		Number of Secondary pins used
USE_SHIELD S	NO		Use shield Windings
LP_nom	1041	μH	Nominal Primary Inductance
LP_Tol	10.0	%	Primary Inductance Tolerance
NP	64.6		Calculated Primary Winding Total Number of Turns
NSM	8		Secondary Main Number of Turns
CMA	518	Cmils/A	Primary Winding Current Capacity
VOR	105.0	V	Reflected Output Voltage
BW	15.30	mm	Bobbin Winding Width
ML	0.00	mm	Safety Margin on Left Width
MR	0.00	mm	Safety Margin on Right Width
FF	33	%	Actual Transformer Fit Factor. 100% signifies fully utilized winding window
AE	52.50	mm ²	Core Cross Sectional Area
ALG	224	nH/T ²	Gapped Core Effective Inductance
BM	2675	Gauss	Maximum Flux Density
BAC	453	Gauss	AC Flux Density for Core Loss
LG	0.256	mm	Estimated Gap Length
L_LKG	31.24	μH	Estimated primary leakage inductance
LSEC	15	nH	Secondary Trace Inductance

Primary Winding Section 1

<i>Var</i>	<i>Value</i>	<i>Units</i>	<i>Description</i>
NP1	65		Rounded (Integer) Number of Primary winding turns in the first section of primary
Wire Size	26	AWG	Wire size of primary winding
Winding Type	Single (x1)		Primary winding number of parallel wire strands
L	1.92		Primary Number of Layers
DC Copper Loss	0.10	W	Primary 1 DC Losses

Output 1

<i>Var</i>	<i>Value</i>	<i>Units</i>	<i>Description</i>
VO	12.00	V	Output Voltage
IO	1.80	A	Output Current
VOUT_ACTUAL	12.00	V	Actual Output Voltage
NS	8		Secondary Number of Turns
Wire Size	25	AWG	Wire size of secondary winding
Winding Type	Bifilar (x2)		Output winding number of parallel strands
L_S_OUT	0.68		Secondary Output Winding Layers
DC Copper Loss	0.27	W	Secondary DC Losses
VD	1.00	V	Output Winding Diode Forward Voltage Drop
PIVS	58	V	Output Rectifier Maximum Peak Inverse Voltage
ISP	6.05	A	Peak Secondary Current
ISRMS	3.19	A	Secondary RMS Current
RTH_DIODE	31.05	°C/W	Output Diode Maximum Thermal Resistance
OD_HSINK_TYPE	2 Oz (70 μ) Copper PCB		Output Diode Heatsink Type

OD_HSINK_A REA	1218	mm ²	Output Diode Heatsink Area
CO	1000 x 1	μF	Output Capacitor
IRIPPLE	2.63	A	Output Capacitor RMS Ripple Current
Expected Lifetime	42869	hr	Expected Lifetime of Output Capacitor

Output 2

<i>Var</i>	<i>Value</i>	<i>Units</i>	<i>Description</i>
VO	-12.00	V	Output Voltage
IO	0.10	A	Output Current
VOUT_ACTU AL	-12.00	V	Actual Output Voltage
NS	8		Secondary Number of Turns
Wire Size	32	AWG	Wire size of secondary winding
Winding Type	Single (x1)		Output winding number of parallel strands
L_S_OUT	0.21		Secondary Output Winding Layers
DC Copper Loss	0.01	W	Secondary DC Losses
VD	1.00	V	Output Winding Diode Forward Voltage Drop
PIVS	58	V	Output Rectifier Maximum Peak Inverse Voltage
ISP	0.34	A	Peak Secondary Current
ISRMS	0.18	A	Secondary RMS Current
RTH_DIODE	561.78	°C/W	Output Diode Maximum Thermal Resistance
OD_HSINK_T YPE	2 Oz (70 μ) Copper PCB		Output Diode Heatsink Type
OD_HSINK_A REA	52	mm ²	Output Diode Heatsink Area
CO	47 x 1	μF	Output Capacitor
IRIPPLE	0.15	A	Output Capacitor RMS Ripple Current
Expected Lifetime	25263	hr	Expected Lifetime of Output Capacitor

Feedback Circuit

<i>Var</i>	<i>Value</i>	<i>Units</i>	<i>Description</i>
DUAL_OUTP UT_FB_FLAG	NO		Dual Output Feedback regulations use flag
SF_FLAG	NO		Soft Finish Circuits use flag
TYPE_3CTRL _FLAG	NO		Phase Boost Network flag

The regulation and tolerances do not account for thermal drifting and component tolerance of the output diode forward voltage drop and voltage drops across the LC post filter. The actual voltage values are estimated at full load only.

Please verify cross regulation performance on the bench.

Bill Of Materials

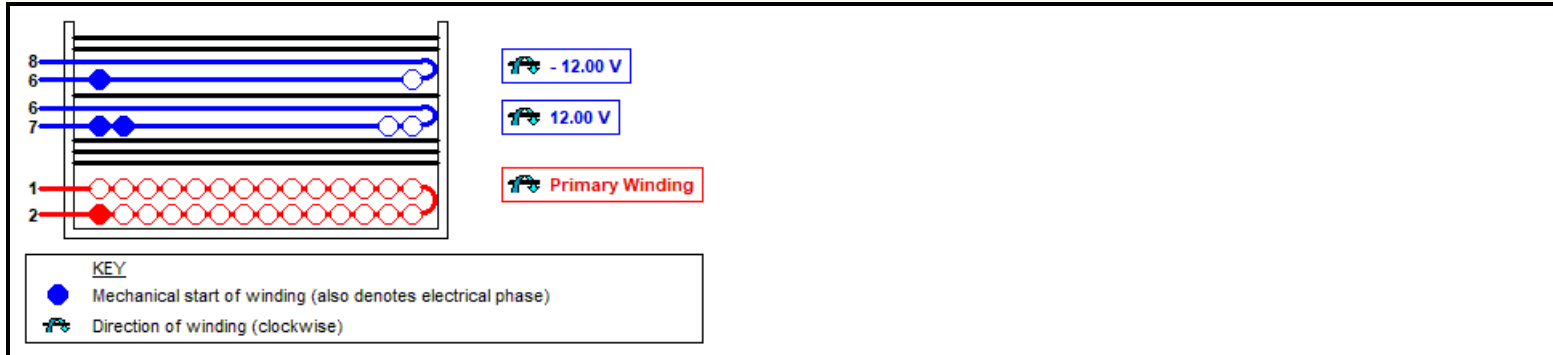
Item #	Quantity	Part Ref	Value	Description	Mfg	Mfg Part Number
1	1	C1	100 nF	100 nF, 275 VAC, Film, X Class	Kemet	R46KI310000M1K
2	1	C2	56 μ F	56 μ F, 400 V, High Voltage Al Electrolytic, (35 mm x 12.5 mm)	United Chemi-Con	EPAG400VB56RM12X35LL
3	1	C3	2.7 nF	2.7 nF, 1 kV, High Voltage Ceramic	Panasonic	ECK-D3A272KBP
4	1	C4	10 μ F	10 μ F, 16 V, Ceramic, X7R	TDK	C3216X7R1C106K
5	1	C5	2.2 nF	2.2 nF, 250 VAC, Ceramic, Y Class	TDK	CD12-E2GA222MYNS
6	2	C6, C7	27 pF	27 pF, 100 V, Ceramic, C0G	Epcos	B37979N1270J000
7	1	C8	47 μ F	47 μ F, 25 V, Electrolytic, Super Low ESR, 300 m Ω , (11 mm x 5 mm)	United Chemi-Con	EKZE250ELL470ME11D
8	1	C9	1000 μ F	1000 μ F, 35 V, Electrolytic, Super Low ESR, 18 m Ω , (25 mm x 12.5 mm)	United Chemi-Con	EKZE350ELL102MK25S
9	1	C10	100 μ F	100 μ F, 16 V, Electrolytic, Low ESR, 250 m Ω , (11.5 mm x 6.3 mm)	United Chemi-Con	ELXZ160ELL101MFB5D
10	1	C11	100 nF	100 nF, 16 V, Ceramic, X7R	TDK	C1005X7R1C104K
11	4	D1, D2, D3, D4	1N4006	800 V, 1 A, Standard Recovery, DO-41	Vishay	1N4006
12	1	D5	FR106	800 V, 1 A, Fast Recovery, 250 ns, DO-41	Diodes Inc.	FR106
13	1	D6	BAV20	200 V, 0.2 A, Fast Recovery, 50 ns, DO-35	Vishay	BAV20
14	1	D7	UF5402	200 V, 3 A, Ultrafast Recovery, 50 ns, DO-201AD	Vishay	UF5402
15	1	F1	1 A	250 VAC, 1 A, Radial TR5, Time Lag Fuse	Littelfuse / Wickmann(R)	37411000410
16	1	L1	6 mH	6 mH, 1.6 A	Panasonic	ELF18N016
17	1	L2	3.3 μ H	3.3 μ H, 2.66 A	Bourns Inc.	RL822-3R3K-RC
18	1	R1	27 k Ω	27 k Ω , 5 %, 2 W, Metal Oxide Film	Generic	
19	1	R2	15 Ω	15 Ω , 5 %, 0.25 W, Carbon Film	Generic	
20	2	R3, R4	2 M Ω	2 M Ω , 5 %, 0.25 W, Carbon Film	Generic	
21	2	R5, R6	390 Ω	390 Ω , 5 %, 0.25 W, Carbon Film	Generic	
22	1	R7	210 Ω	210 Ω , 1 %, 0.125 W, Metal Film	Generic	
23	1	R8	1 k Ω	1 k Ω , 5 %, 0.125 W, Carbon Film	Generic	
24	1	R9	43.2 k Ω	43.2 k Ω , 1 %, 0.125 W, Metal Film	Generic	
25	1	R10	11.3 k Ω	11.3 k Ω , 1 %, 0.125 W, Metal Film	Generic	
26	1	RT1	16 Ω	NTC Thermistor 16 Ω , 1.7 A	Thermometrics	CL180
27	1	RV1	V275LA4P	275 V, 23 J, 7 mm, RADIAL, MOV	Littelfuse	V275LA4P
28	1	T1	E25/13/7 (EF25)	NC-2H (Nicera) or Equivalent Core Material See Transformer Construction's Materials List for complete information	Epcos	B66317-G-X127
29	1	U1	TNY290PG	TinySwitch-4, TNY290PG, DIP-8	Power Integrations	TNY290PG
30	1	U2	PS2501-1-K-A	Optocoupler PS2501-1-K-A, 80 V, CTR 300 - 600 %, 4-DIP	CEL	PS2501-1-K-A
31	1	U3	TL431CLPM	2.495 V, Shunt Regulator IC, 2 %, TO-92	Texas Instruments	TL431CLPM

32	1			1218 mm ² area on Copper PCB. 2 oz (70 μm) thickness. Heatsink for use with Diode D7.	Custom	
33	1			52 mm ² area on Copper PCB. 2 oz (70 μm) thickness. Heatsink for use with Diode D6.	Custom	
34	1			262 mm ² area on Copper PCB. 2 oz (70 μm) thickness. Heatsink for use with Device U1.	Custom	

Electrical Diagram



Mechanical Diagram



Winding Instruction

Primary Winding
 Start on pin(s) 2 and wind 65 turns (x 1 filar) of item [5], in 2 layer(s) from left to right. At the end of 1st layer, continue to wind the next layer from right to left. On the final layer, spread the winding evenly across entire bobbin. Finish this winding on pin(s) 1.
 Add 3 layers of tape, item [3], for insulation.

Secondary Winding
 Start on pin(s) 7 and wind 8 turns (x 2 filar) of item [6]. Spread the winding evenly across entire bobbin. Wind in same rotational direction as primary winding. Finish this winding on pin(s) 6.
 Add 1 layer of tape, item [3], for insulation.
 Start on pin(s) 6 and wind 8 turns (x 1 filar) of item [7]. Spread the winding evenly across entire bobbin. Finish this winding on pin(s) 8.
 Add 2 layers of tape, item [3], for insulation.

Core Assembly
 Assemble and secure core halves. Item [1].

Varnish
 Dip varnish uniformly in item [4]. Do not vacuum impregnate.

Comments

1. For non margin wound transformers use triple insulated wire for all secondary windings.

Materials

Item	Description
[1]	Core: E25/13/7 (EF25), NC-2H (Nicera) or Equivalent, gapped for ALG of 224 nH/T ²
[2]	Bobbin: Generic, 5 pri. + 5 sec.
[3]	Barrier Tape: Polyester film [1 mil (25 µm) base thickness], 15.30 mm wide
[4]	Varnish
[5]	Magnet Wire: 26 AWG, Solderable Double Coated
[6]	Triple Insulated Wire: 25 AWG
[7]	Triple Insulated Wire: 32 AWG

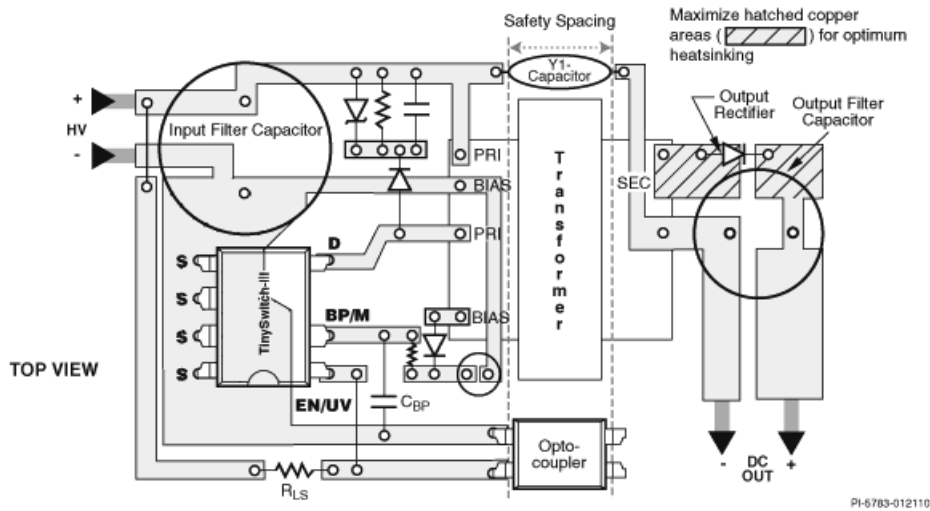
Electrical Test Specifications

Parameter	Condition	Spec
Electrical Strength, VAC	60 Hz 1 second, from pins 1,2 to pins 6,7,8.	3000
Nominal Primary Inductance, µH	Measured at 1 V pk-pk, typical switching frequency, between pin 1 to pin 2, with all other Windings open.	1041
Tolerance, ±%	Tolerance of Primary Inductance	10.0
Maximum Primary Leakage, µH	Measured between Pin 1 to Pin 2, with all other Windings shorted.	31.24

Although the design of the software considered safety guidelines, it is the user's responsibility to ensure that the user's power supply design meets all applicable safety requirements of user's product.

The products and applications illustrated herein (including circuits external to the products and transformer construction) may be covered by one or more U.S. and foreign patents or potentially by pending U.S. and foreign patent applications assigned to Power Integrations. A complete list of Power Integrations' patents may be found at www.power.com.

Board Layout Recommendations



Click on the "Show me" icon to highlight relevant areas on the sample layout.

	Description	Show Me
1	Maximize source area for good heat-sinking	
2	Keep drain trace short	
3	The BYPASS pin capacitor should be located as close as possible to the BYPASS and SOURCE pins	
4	Keep noisy traces away from EN/UV pin	
5	Route bias winding currents back to the bulk cap	
6	Keep clamp loop short	
7	Connect Y capacitor to the B+ rail on the primary side for better surge immunity. Keep Y capacitor traces short	
8	The area of the loop connecting the secondary winding, the output diode and the output filter capacitor should be minimized	